
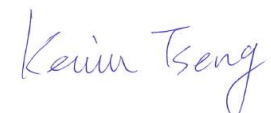


**To : Dear Valued Customers**

**Product/Process Change Notice**

We hereby submit PCN for your review and approval.

<p>Application or type :</p> <p>0201/DFN0603 package series assembly site add</p>	
<p>Detail of the change :</p> <p>0201/DFN0603 package internal structure add</p>	
<p>Current :</p> <p>Current copper substrate.</p> <p align="center">Dimensions in inches and (millimeter)</p>	<p>After the change :</p> <p>New copper substrate.</p> <p align="center">Dimensions in inches and (millimeter)</p>
<p>Reason for the change :</p> <p>This notification is to advise our customers that we will add new copper substrate source of 0201/DFN0603 package series. There is no change to the product electrical specifications. Attach new reliability reports.</p> <p>Information of Supplier :</p> <p>Company Name : Comchip Technology Co., Ltd. Address : No.586, Jianguo Rd., Yingge Dist., New Taipei City, Taiwan</p>	

Evaluation items : Part No. affected :													
	<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="padding: 2px;">CDBZ0130L-HF</td> <td style="padding: 2px;">CZRZ3V3B-HF</td> </tr> <tr> <td style="padding: 2px;">CDBZ0130R-HF</td> <td style="padding: 2px;">CZRZ4V7B-HF</td> </tr> <tr> <td style="padding: 2px;">CPDZ9V0U-HF</td> <td style="padding: 2px;">CZRZ5V1B-HF</td> </tr> <tr> <td style="padding: 2px;">CPDZ3V3U-HF</td> <td style="padding: 2px;">CZRZ5V6B-HF</td> </tr> <tr> <td style="padding: 2px;">CPDZ5V0C-HF</td> <td style="padding: 2px;">CZRZ6V8B-HF</td> </tr> <tr> <td style="padding: 2px;">CDSZ01100-HF</td> <td style="padding: 2px;"></td> </tr> </table>	CDBZ0130L-HF	CZRZ3V3B-HF	CDBZ0130R-HF	CZRZ4V7B-HF	CPDZ9V0U-HF	CZRZ5V1B-HF	CPDZ3V3U-HF	CZRZ5V6B-HF	CPDZ5V0C-HF	CZRZ6V8B-HF	CDSZ01100-HF	
CDBZ0130L-HF	CZRZ3V3B-HF												
CDBZ0130R-HF	CZRZ4V7B-HF												
CPDZ9V0U-HF	CZRZ5V1B-HF												
CPDZ3V3U-HF	CZRZ5V6B-HF												
CPDZ5V0C-HF	CZRZ6V8B-HF												
CDSZ01100-HF													
Implemented from :													
Effective Date : 17 Nov 2017													
R&D Dept. Signature :	QA Dept. Signature :												
													

### **Answer To PCN**

Please complete the form below duly signed and fax back to Comchip Technology Co.

Please select your answer 1. Approved this PCN 2. Approved this PCN with conditions 3. Disapproved this PCN	Date  Responsibility By
Please specify the condition or explain the reason if you select 2 or 3.	

Unless a Comchip Technology Co., Ltd. Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.



**Technology Co., Ltd.**

## **Reliability Test Report**

**Part NO.:** CDBZ0130L-HF  
**Diodes**

**Date:** 201+.10.2\$

ComChip Technology Co., Ltd.

Add. : No. 586, Jianguo Rd., Yingge Dist.,  
New Taipei City 23943, Taiwan

Tel. : 886-2-8677-6675  
FAX : 886-2-8677-6672

QR-0803-02 Rev.F

**Reliability Test Summary**

P / N : CDBZ0130L-HF L / N : N/A  
 Criteria :  $V_F \leq 350$  mV @  $I_F = 10$  mA  $I_R \leq 5$   $\mu$ A @  $V_R = 10$  V  $V_Z \geq 30.0$  V @  $I_Z = 0.1$  mA

No	Test Item	Test Condition	Test Foundation	Failure qty'	S.S	Parameter	X Bar	S Dev	Max	Min	
1	Solderability	Dip in flux Time=5sec. Temp.of solder Pot=245±5℃ · Time= 5~10 sec.	MIL-STD-750 Method 2026	0	22	Before	V <sub>F</sub> (mV)	X			
							I <sub>R</sub> (μA)				
							V <sub>Z</sub> (V)				
				0	22	After	V <sub>F</sub> (mV)				
							I <sub>R</sub> (μA)				
							V <sub>Z</sub> (V)				
2	Soldering Heat	Temp of solder pot=260±5℃ · Time= 10~12 sec	MIL-STD-750 Method 2031	0	22	Before	V <sub>F</sub> (mV)	295.1818	1.1807	299.0000	294.0000
							I <sub>R</sub> (μA)	1.6284	0.0805	1.7602	1.4084
							V <sub>Z</sub> (V)	42.4589	0.2088	42.6669	41.7666
				0	22	After	V <sub>F</sub> (mV)	296.5000	3.6613	312.0000	294.0000
							I <sub>R</sub> (μA)	1.6069	0.1438	1.9685	1.4374
							V <sub>Z</sub> (V)	42.4026	0.1854	42.5754	41.9344
3	Temperature Cycle	Tstg(-40℃)to Tstg(125℃) dwelled for 30 min and transfer time not exceed 1 min; 20 cycles	MIL-STD-750 Method 1051	0	22	Before	V <sub>F</sub> (mV)	295.9545	0.4857	297.0000	295.0000
							I <sub>R</sub> (μA)	1.5137	0.0293	1.5832	1.4641
							V <sub>Z</sub> (V)	42.4221	0.2018	42.6364	41.9802
				0	22	After	V <sub>F</sub> (mV)	296.4545	0.8004	299.0000	295.0000
							I <sub>R</sub> (μA)	1.4460	0.0177	1.4992	1.4092
							V <sub>Z</sub> (V)	42.4359	0.1954	42.6059	41.9802
4	Thermal Shock Test	T <sub>a1</sub> = 100℃ Time = 10 min then t <sub>a2</sub> = 0 ℃, Tim= 10 min for 20 cycles,transfer time must not exseed 5sec.	MIL-STD-750 Method 1056	0	22	Before	V <sub>F</sub> (mV)	294.4091	0.7964	295.0000	294.0000
							I <sub>R</sub> (μA)	1.7022	0.0405	1.6602	1.6435
							V <sub>Z</sub> (V)	42.4519	0.2960	42.5143	42.4075
				0	22	After	V <sub>F</sub> (mV)	297.2273	1.0204	298.0000	298.0000
							I <sub>R</sub> (μA)	1.4149	0.0304	1.3901	1.3833
							V <sub>Z</sub> (V)	42.3645	0.2885	42.4533	42.3312
5	Steady State Operation Life Test	I=100mA Time=1000hrs.	MIL-STD-750 Method 1027	0	22	Before	V <sub>F</sub> (mV)	297.5909	1.6521	303.0000	293.0000
							I <sub>R</sub> (μA)	1.3595	0.0868	1.7396	1.3001
							V <sub>Z</sub> (V)	42.2840	0.2919	42.5296	41.2477
				0	22	After	V <sub>F</sub> (mV)	298.6818	1.1291	301.0000	295.0000
							I <sub>R</sub> (μA)	1.2479	0.0506	1.4527	1.2108
							V <sub>Z</sub> (V)	42.2556	0.2958	42.4838	41.2172
6	High Temperature Reverse Bias Life	V <sub>R</sub> = G V Temp.85±5℃ (depend on product) Time 1000hrs.	MIL-STD-750 Method 1038	0	22	Before	V <sub>F</sub> (mV)	299.0909	1.6877	306.0000	298.0000
							I <sub>R</sub> (μA)	1.2743	0.0177	1.3077	1.2452
							V <sub>Z</sub> (V)	42.3430	0.1650	42.5143	41.7971
				0	22	After	V <sub>F</sub> (mV)	299.2273	0.9223	301.0000	297.0000
							I <sub>R</sub> (μA)	1.2226	0.0344	1.3123	1.1788
							V <sub>Z</sub> (V)	42.3999	0.1654	42.5754	41.8734
7	Intermittent Forward Operation Life	I <sub>F</sub> =100mA ON 1.5hrs/OFF 0.5hrs Test Time : 500Cycles	MIL-STD-750 Method 1036	0	22	Before	V <sub>F</sub> (mV)	297.4091	0.5903	298.0000	296.0000
							I <sub>R</sub> (μA)	1.3770	0.0630	1.6343	1.3154
							V <sub>Z</sub> (V)	42.3770	0.1950	42.5601	41.7666
				0	22	After	V <sub>F</sub> (mV)	298.7273	1.2025	303.0000	298.0000
							I <sub>R</sub> (μA)	1.2339	0.0185	1.2681	1.1979
							V <sub>Z</sub> (V)	42.3492	0.2003	42.5143	41.7361

**Reliability Test Summary**

P / N : CDBZC0130L-HF      L / N : N/A  
 Criteria : VF ≤ 350 mV @IF= 10 mA      IR ≤ 5 uA @VR= 10 V      VZ ≥ 30.0 V @IZ= 0.1 mA

No	Test Item	Test Condition	Test Foundation	Failure qty'	S.S	Parameter	X Bar	S Dev	Max	Min	
8	Pressure Cooker Test	Ta= 121°C Pressure= 15 Psi Time= 4 hrs	JESD 22-A102	0	22	Before	VF (mV)	294.6364	1.0022	296.0000	291.0000
							IR (μA)	1.6669	0.0590	1.9227	1.6274
							VZ (V)	42.4866	0.3311	42.6822	41.0951
				0	22	After	VF (mV)	297.8636	0.9409	300.0000	295.0000
							IR (μA)	1.3693	0.0461	1.5672	1.3337
							VZ (V)	42.3818	0.3439	42.5754	40.9578
9	Boiling	5 Hours at 100°C Water.	-----	0	22	Before	VF (mV)	293.7727	1.3068	297.0000	291.0000
							IR (μA)	1.7866	0.0648	2.0036	1.7213
							VZ (V)	42.4484	0.3805	42.6974	41.4766
				0	22	After	VF (mV)	297.0455	1.7856	301.0000	294.0000
							IR (μA)	1.4596	0.0556	1.6450	1.4123
							VZ (V)	42.3770	0.3537	42.6517	41.4766
10	High Temperature Storage Life	Ta= 125°C. Time= 1000 hrs	MIL-STD-750 Method 1031	0	22	Before	VF (mV)	297.0000	1.2724	298.0000	292.0000
							IR (μA)	1.4341	0.0872	1.8174	1.3894
							VZ (V)	42.4033	0.2272	42.6059	41.6292
				0	22	After	VF (mV)	297.0909	2.1137	303.0000	292.0000
							IR (μA)	1.4126	0.0894	1.7816	1.3383
							VZ (V)	42.4623	0.2202	42.6211	41.7208
11	Humidity	Ta= 85 °C RH= 85% Time=1000 hrs	EIAJ ED-4701	0	22	Before	VF (mV)	296.6818	1.0861	298.0000	293.0000
							IR (μA)	1.4691	0.0559	1.6671	1.4084
							VZ (V)	42.3791	0.3206	42.5906	41.4461
				0	22	After	VF (mV)	297.4545	3.9367	314.0000	293.0000
							IR (μA)	1.4732	0.0582	1.6709	1.4214
							VZ (V)	42.4512	0.3265	42.6669	41.4919

Conclusion:

1. 22CC22
2. I bSee

Approval: Kevin Tseng

Prepare: Judy Lin



**Technology Co., Ltd.**

## **Reliability Test Report**

**Part NO.:**                     CZRZ5V1B-HF                      
**Diodes**

**Date:**                     2017.04.17                    

ComChip Technology Co., Ltd.

Add. : No. 586, Jianguo Rd., Yingge Dist.,  
New Taipei City 23943, Taiwan

Tel. : 886-2-8677-6675  
FAX : 886-2-8677-6672

Date: 2017/4/17

## Reliability Test Summary

P / N : CZRZ5V1B-HF

L / N : N/A

Criteria : ZZK ≤ 500 ohm @IZK= 0.5 mA VF ≤ 900 mV @IF=10mA 5.37 ≥ VZ ≥ 4.84 V @IZ= 5 mA  
ZZT ≤ 80 ohm @IZT= 5 mA IR ≤ 2 uA @VR=1.5V

No	Test Item	Test Condition	Test Foundation	Failure qty'	S.S	Parameter	X Bar	S Dev	Max	Min	
1	Solderability	Dip in flux Time=5sec. Temp.of solder Pot=245±5℃ , Time= 5~10 sec.	MIL-STD-750 Method 2026	0	22	Before	ZZK (ohm)	N/A			
							ZZT (ohm)				
							VF (mV)				
							VZ (V)				
				0	22	After	ZZK (ohm)				
							ZZT (ohm)				
							VF (mV)				
							IR (uA)				
2	Soldering Heat	Temp of solder pot=260±5℃ , Time= 10~12 sec	MIL-STD-750 Method 2031	0	22	Before	ZZK (ohm)	116.3236	2.0487	119.9500	112.0900
							ZZT (ohm)	4.3673	0.0661	4.5200	4.2800
							VF (mV)	830.3729	0.7044	832.7382	829.3810
							VZ (V)	5.1115	0.0042	5.1207	5.1051
				0	22	After	IR (uA)	0.0240	0.0230	0.0554	0.0010
							ZZK (ohm)	117.4373	3.9017	130.3000	112.0900
							ZZT (ohm)	4.5295	0.1775	4.8700	4.2800
							VF (mV)	836.2133	10.7025	868.4466	828.9232
0	22	After	VZ (V)	5.1135	0.0068	5.1335	5.1019				
			IR (uA)	0.0132	0.0185	0.0629	0.0010				
			ZZK (ohm)	115.3982	2.0824	118.1600	110.1900				
			ZZT (ohm)	4.3891	0.0821	4.6400	4.2800				
3	Temperature Cycle	Tstg(-55 ℃)to Tstg(150 ℃) dwelled for 30 min and transfer time not exceed 1 min; 20 cycles	MIL-STD-750 Method 1051	0	22	Before	VF (mV)	831.3925	0.7336	833.1960	830.2966
							VZ (V)	5.1112	0.0045	5.1193	5.1051
							IR (uA)	0.0163	0.0166	0.0482	0.0010
							ZZK (ohm)	116.9014	2.3040	121.1400	113.2800
				0	22	After	ZZT (ohm)	4.5086	0.1209	4.8700	4.4000
							VF (mV)	831.4134	0.7023	833.1960	830.1440
							VZ (V)	5.1113	0.0053	5.1202	5.0987
							IR (uA)	0.0093	0.0042	0.0160	0.0010
4	Thermal Shock Test	Tal = 100 ℃ Time = 10 min then ta2= 0 ℃, Tim= 10 min for 20 cycles, transfer time must not exceed 5sec.	MIL-STD-750 Method 1056	0	22	Before	ZZK (ohm)	115.0300	1.6919	117.5700	111.3800
							ZZT (ohm)	4.4918	0.1710	4.9900	4.2800
							VF (mV)	833.6677	2.1785	840.3682	831.9752
							VZ (V)	5.1093	0.0041	5.1184	5.1037
				0	22	After	IR (uA)	0.0103	0.0112	0.0448	0.0010
							ZZK (ohm)	116.9173	4.2587	133.9900	112.6900
							ZZT (ohm)	4.4586	0.0948	4.6400	4.2800
							VF (mV)	833.9937	5.4766	856.8490	830.9070
0	22	After	VZ (V)	5.1103	0.0056	5.1307	5.1051				
			IR (uA)	0.0197	0.0202	0.0571	0.0010				
			ZZK (ohm)	113.5109	1.9460	116.9700	109.5900				
			ZZT (ohm)	4.2655	0.0746	4.4000	4.1600				
5	High Temperature Reverse Bias Life	VZ= 4.08V Temp.150±5℃ (depend on product) Time 1000hrs	MIL-STD-750 Method 1038	0	22	Before	VF (mV)	836.0677	5.4611	837.9266	811.6794
							VZ (V)	5.0994	0.0208	5.1124	5.0085
							IR (uA)	0.0198	0.0164	0.0447	0.0010
							ZZK (ohm)	113.3005	2.4477	120.5400	109.5900
				0	22	After	ZZT (ohm)	4.3018	0.1682	4.6400	3.8000
							VF (mV)	831.7602	5.3578	833.9590	815.1892
							VZ (V)	5.1095	0.0058	5.1193	5.0982
							IR (uA)	0.0115	0.0124	0.0357	0.0010

Date: 2017/4/17

## Reliability Test Summary

P / N : CZRZ5V1B-HF

L / N : N/A

Criteria : ZZK ≤ 500 ohm @IZK= 0.5 mA VF ≤ 900 mV @IF=10mA 5.37 ≥ VZ ≥ 4.84 V @IZ= 5 mA  
 ZZT ≤ 80 ohm @IZT= 5 mA IR ≤ 2 uA @VR=1.5V

No	Test Item	Test Condition	Test Foundation	Failure qty'	S.S	Parameter	X Bar	S Dev	Max	Min	
6	Pressure Cooker Test	Ta= 121°C Pressure= 15 Psi Time= 4 hrs	JESD 22-A102	0	22	Before	ZZK (ohm)	116.5823	2.1587	119.9500	112.6900
							ZZT (ohm)	4.3945	0.0943	4.7600	4.2800
							VF (mV)	830.0816	0.5684	830.7544	828.6180
							VZ (V)	5.1110	0.0050	5.1198	5.0992
				0	22	After	ZZK (ohm)	114.9432	2.1847	118.1600	109.0000
							ZZT (ohm)	4.4486	0.1071	4.8700	4.4000
							VF (mV)	831.8503	1.1377	835.1798	830.2966
							IR (uA)	0.0102	0.0064	0.0368	0.0032
7	Boiling	5 Hours at 100°C Water.	-----	0	22	Before	ZZK (ohm)	117.2059	2.2040	119.9500	112.6900
							ZZT (ohm)	4.5409	0.1957	5.2300	4.4000
							VF (mV)	830.3798	1.7650	835.7902	828.3128
							VZ (V)	5.1131	0.0052	5.1225	5.1065
				0	22	After	ZZK (ohm)	117.1718	2.4213	120.5400	112.6900
							ZZT (ohm)	4.7645	0.3400	5.4700	4.3000
							VF (mV)	836.8237	8.1550	858.3750	828.9232
							IR (uA)	0.0107	0.0076	0.0220	0.0010
8	High Temperature Storage Life	Ta= 150°C. Time= 1000 hrs	MIL-STD-750 Method 1032	0	22	Before	ZZK (ohm)	116.7782	2.8404	122.4500	110.1900
							ZZT (ohm)	4.4650	0.2372	5.4700	4.2800
							VF (mV)	829.6515	2.0699	838.0792	827.2446
							VZ (V)	5.1133	0.0057	5.1234	5.1051
				0	22	After	ZZK (ohm)	114.9768	2.6481	119.3500	109.0000
							ZZT (ohm)	4.4764	0.0872	4.6400	4.2800
							VF (mV)	829.8874	1.1414	831.8226	827.2446
							IR (uA)	0.0124	0.0112	0.0300	0.0010
9	Humidity	Ta= 85 °C RH= 85% Time=1000 hrs	EIAJ ED-4701	0	22	Before	ZZK (ohm)	118.1945	2.4055	121.8500	110.1900
							ZZT (ohm)	4.4664	0.1002	4.6400	4.1800
							VF (mV)	827.6885	0.5842	829.2284	826.7868
							VZ (V)	5.1128	0.0065	5.1239	5.0909
				0	22	After	ZZK (ohm)	119.2236	4.5211	137.0800	112.0900
							ZZT (ohm)	4.5782	0.2508	5.1700	4.4000
							VF (mV)	829.5475	8.2400	864.7842	823.8874
							IR (uA)	0.0155	0.0164	0.0801	0.0010

Conclusion:

- 此次共有 9 項實驗
- 工試結果 : PASS

Approval: Kevin Tseng

Prepare: Judy Lin





**Technology Co., Ltd.**

## **Reliability Test Report**

**Part NO.:**                     CZRZ5V6B-HF                      
**Diodes**

**Date:**                     2017.04.17                    

ComChip Technology Co., Ltd.

Add. : No. 586, Jianguo Rd., Yingge Dist.,  
New Taipei City 23943, Taiwan

Tel. : 886-2-8677-6675  
FAX : 886-2-8677-6672

Date: 2017/4/17

## Reliability Test Summary

P / N : CZRZ5V6B-HF

L / N : N/A

Criteria : ZZK ≤ 200 ohm @IZK= 0.5 mA VF ≤ 900 mV @IF=10mA 5.92 ≥ VZ ≥ 5.31 V @IZ= 5 mA  
 ZZT ≤ 60 ohm @IZT= 5 mA IR ≤ 1 uA @VR=2.5V

No	Test Item	Test Condition	Test Foundation	Failure qty'	S.S	Parameter	X Bar	S Dev	Max	Min	
1	Solderability	Dip in flux Time=5sec. Temp.of solder Pot=245±5℃ , Time= 5~10 sec.	MIL-STD-750 Method 2026	0	22	Before	ZZK (ohm)	N/A			
							ZZT (ohm)				
							VF (mV)				
							VZ (V)				
				0	22	After	ZZK (ohm)				
							ZZT (ohm)				
							VF (mV)				
							IR (uA)				
2	Soldering Heat	Temp of solder pot=260±5℃ , Time= 10~12 sec	MIL-STD-750 Method 2031	0	22	Before	ZZK (ohm)	13.3223	0.4106	13.9200	12.7300
							ZZT (ohm)	5.5573	0.0757	5.7100	5.4700
							VF (mV)	832.8353	0.6328	833.6538	831.6700
							VZ (V)	5.6144	0.0043	5.6206	5.6050
				0	22	After	IR (uA)	0.0451	0.0427	0.1220	0.0010
							ZZK (ohm)	13.5923	0.4758	14.5100	12.7300
							ZZT (ohm)	5.7505	0.2682	6.1800	5.0200
							VF (mV)	838.3705	12.1520	887.2164	831.3648
0	22	After	VZ (V)	5.6197	0.0078	5.6403	5.6078				
			IR (uA)	0.0382	0.0579	0.2060	0.0010				
			ZZK (ohm)	13.2945	0.4289	14.5100	12.7300				
			ZZT (ohm)	5.5791	0.0512	5.7100	5.4700				
3	Temperature Cycle	Tstg(-55 ℃)to Tstg(150 ℃) dwelled for 30 min and transfer time not exceed 1 min; 20 cycles	MIL-STD-750 Method 1051	0	22	Before	VF (mV)	831.6700	0.3648	832.2804	831.0596
							VZ (V)	5.6162	0.0044	5.6265	5.6096
							IR (uA)	0.0267	0.0122	0.0686	0.0076
							ZZK (ohm)	13.2945	0.5030	13.9200	12.1300
				0	22	After	ZZT (ohm)	5.5955	0.0583	5.7100	5.4700
							VF (mV)	832.8492	0.3917	833.5012	831.8226
							VZ (V)	5.6149	0.0041	5.6242	5.6087
							IR (uA)	0.0243	0.0118	0.0457	0.0010
4	Thermal Shock Test	Tal = 100 ℃ Time = 10 min then ta2= 0 ℃,Tim= 10 min for 20 cycles, transfer time must not exceed 5sec.	MIL-STD-750 Method 1056	0	22	Before	ZZK (ohm)	13.4895	0.6854	15.8200	12.7300
							ZZT (ohm)	5.7214	0.2009	6.3300	5.4700
							VF (mV)	834.1810	5.3498	857.6120	831.6700
							VZ (V)	5.6177	0.0056	5.6297	5.6091
				0	22	After	IR (uA)	0.0235	0.0267	0.0915	0.0010
							ZZK (ohm)	13.3768	0.5782	14.5100	12.1300
							ZZT (ohm)	5.6877	0.1953	6.1800	5.4700
							VF (mV)	833.5775	5.3958	854.2548	829.6862
0	22	After	VZ (V)	5.6181	0.0051	5.6302	5.6114				
			IR (uA)	0.0298	0.0164	0.0763	0.0010				
			ZZK (ohm)	13.2673	0.4056	14.5100	12.7300				
			ZZT (ohm)	5.4482	0.0797	5.5900	5.3500				
5	High Temperature Reverse Bias Life	VZ= 4.48 V Temp.150±5℃ (depend on product) Time 1000hrs	MIL-STD-750 Method 1038	0	22	Before	VF (mV)	838.6410	0.3894	839.3000	837.4688
							VZ (V)	5.6057	0.0051	5.6146	5.5991
							IR (uA)	0.0320	0.0191	0.0610	0.0010
							ZZK (ohm)	13.5359	0.9103	15.8200	12.7300
				0	22	After	ZZT (ohm)	5.7891	0.3494	6.5400	5.4700
							VF (mV)	841.8387	14.0193	898.3562	835.3324
							VZ (V)	5.6150	0.0071	5.6389	5.6068
							IR (uA)	0.0296	0.0179	0.0534	0.0010

Date: 2017/4/17

## Reliability Test Summary

P / N : CZRZ5V6B-HF

L / N : N/A

Criteria : ZZK ≤ 200 ohm @IZK= 0.5 mA VF ≤ 900 mV @IF=10mA 5.92 ≥ VZ ≥ 5.31 V @IZ= 5 mA  
 ZZT ≤ 60 ohm @IZT= 5 mA IR ≤ 1 uA @VR=2.5V

No	Test Item	Test Condition	Test Foundation	Failure qty'	S.S	Parameter	X Bar	S Dev	Max	Min	
6	Pressure Cooker Test	Ta= 121°C Pressure= 15 Psi Time= 4 hrs	JESD 22-A102	0	22	Before	ZZK (ohm)	13.3209	0.2597	13.9200	12.7300
							ZZT (ohm)	5.5573	0.1059	5.8300	5.4700
							VF (mV)	830.8030	0.3720	831.8226	830.2966
							VZ (V)	5.6190	0.0054	5.6325	5.6119
				0	22	After	ZZK (ohm)	13.2945	0.3421	13.9200	12.7300
							ZZT (ohm)	5.6445	0.0612	5.7100	5.5900
							VF (mV)	832.3081	0.5279	833.5012	831.5174
							IR (uA)	0.0333	0.0198	0.0686	0.0010
7	Boiling	5 Hours at 100°C Water.	-----	0	22	Before	ZZK (ohm)	13.3223	0.4106	13.9200	12.7300
							ZZT (ohm)	5.6036	0.0784	5.8300	5.4700
							VF (mV)	831.9891	2.5273	842.6572	830.4492
							VZ (V)	5.6158	0.0051	5.6325	5.6100
				0	22	After	ZZK (ohm)	13.3759	0.4461	14.5100	12.7300
							ZZT (ohm)	5.6441	0.1451	6.1800	5.4700
							VF (mV)	831.0388	1.1596	834.5694	829.5336
							IR (uA)	0.0370	0.0334	0.0915	0.0010
8	High Temperature Storage Life	Ta= 150°C. Time= 1000 hrs	MIL-STD-750 Method 1032	0	22	Before	ZZK (ohm)	15.5391	10.1441	60.9200	12.7300
							ZZT (ohm)	5.7636	0.5032	7.9700	5.4700
							VF (mV)	831.3301	0.8644	833.5012	830.1440
							VZ (V)	5.6178	0.0068	5.6274	5.5963
				0	22	After	ZZK (ohm)	15.4805	9.7433	59.0200	12.7300
							ZZT (ohm)	5.8968	0.4895	7.9700	5.5900
							VF (mV)	831.8295	12.2546	886.1482	826.9394
							IR (uA)	0.0292	0.0192	0.0763	0.0010
9	Humidity	Ta= 85 °C RH= 85% Time=1000 hrs	EIAJ ED-4701	0	22	Before	ZZK (ohm)	13.5386	0.4332	14.5100	12.7300
							ZZT (ohm)	5.6282	0.0936	5.9500	5.4700
							VF (mV)	830.3868	0.9356	833.8064	829.0758
							VZ (V)	5.6185	0.0049	5.6270	5.6105
				0	22	After	ZZK (ohm)	13.4036	0.4958	14.5100	12.7300
							ZZT (ohm)	5.6768	0.1473	6.1800	5.4700
							VF (mV)	828.8677	3.1173	842.3520	827.0920
							IR (uA)	0.0274	0.0153	0.0610	0.0010

Conclusion:

- 222K222
- Á bSee
- Á
- Á
- Á

Approval: Kevin Tseng

Prepare: Judy Lin